

20-3060 FR POTTING AND ENCAPSULATING EPOXY RESIN

DESCRIPTION:

20-3060 is a 100% reactive resin which does not contain any solvents, diluents, plasticizers or additives which downgrade physical, thermal, and electrical insulation properties.

20-3060 is a filled system resulting in excellent dimensional stability and extremely low shrinkage. 20-3060 is characterized by exceptional resistance to impact, vibration, and thermal shock. In addition, this versatile resin system is machinable and ideal for use with meter mix dispensing equipment.

Due to its high purity, 20-3060 offers the ultimate in physical, thermal and electrical insulation properties. The cured polymer exhibits excellent resistance to chemicals, moisture, solvents and environmental exposure.

20-3060 is recommended for applications requiring the optimum in over-all properties and where rigid or flexible wire leads protrude directly from the encapsulant. This system eliminates microscopic cracking when leads are flexed. It also adheres extremely well to lead materials, such as vinyl, neoprene, natural rubber, etc...

20-3060 has found wide acceptance as an encapsulant for applications such as transformers, coils, chokes, solenoids, resistors, modules, microcircuitry, resistors, capacitors, etc... 20-3060 has been formulated for ease in handling and its low viscosity aids in pouring, filling voids and air pockets. In addition, the fillers in 20-3060 have been dispersed to minimize any heavy settling.

20-3060 FR is the flame retardant version of the 20-3060. It meets the flame out requirements of UL 94-V0.

The engineering staff at Epoxies, Etc... is at your service to answer questions about particular requirements. Sample kits are available from stock.



TYPICAL SPECIFICATIONS:

Mix Viscosity @ 25°C cps	10,000
Pot Life, 200 gram mass @ 25°C	1.30 HRS.
Specific Gravity, 25°C/25°C, mixed	1.52
Hardness, Shore D	82
Linear Shrinkage, %	.50
Tensile Strength, psi	10,000
Compressive Strength, psi	22,500
Operating Temp. Range, °C	-50 to +135
Dielectric Strength, Volts/Mil	460
Dielectric Constant at 100 HZ	4.51
Volume Resistivity, OHM-CM	3.99 x 10 ¹⁴
Dissipation Factor, 100 HZ	.01
Thermal Conductivity, BTU/hr/ft ² /°F/in.	3.0

INSTRUCTIONS FOR USE:

A. ROOM TEMPERATURE CURING CATALYST 148

1. By weight, thoroughly mix 15 parts catalyst 148 to 100 parts 20-3060 resin.
2. Pour and cure 24 hrs. at room temperature or 2 hours at 60° C.

B. ROOM TEMPERATURE CURING CATALYST 150

1. By weight, thoroughly mix 17 parts catalyst 150 to 100 parts 20-3060 resin.
2. Pour and cure 24 hrs. at room temperature or 2 hours at 60°C.

C. HEAT CURING CATALYST 105

1. By weight thoroughly mix 8 parts catalyst 105 to 100 parts 20-3060 resin.
2. Pour and cure accordingly to one of the following cure schedules:
 - a) 80°C 12 hours
 - b) 100°C 2-4 hours
 - c) 120°C 30-60 minutes

D. By weight, thoroughly mix 7 parts catalyst 190 to 100 parts 20-3060 resin.

IMPORTANT:

The information in this brochure is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

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